

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT5410933

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TSUNG-SHENG KUO	02/01/2018
HSU-SHUI LIU	02/07/2018
JIUN-RONG PAI	02/07/2018
SHOU-WEN KUO	02/07/2018
WEN-CHIN KAN	02/07/2018
YANG-ANN CHU	02/05/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
<b>Street Address:</b>	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK,
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	30078
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15876225
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	USA@JCIPGROUP.COM
<b>Correspondent Name:</b>	JCIPRNET
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<b>Address Line 4:</b>	TAIPEI, TAIWAN 10099
<b>ATTORNEY DOCKET NUMBER:</b>	73168-US-PA
<b>NAME OF SUBMITTER:</b>	BELINDA LEE
<b>SIGNATURE:</b>	/Belinda Lee/
<b>DATE SIGNED:</b>	03/07/2019
<b>Total Attachments: 3</b>	
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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

Declaration Submitted With Initial Filing

OR

Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

**DETAPING MACHINE AND DETAPING METHOD**

(Title of the Invention)

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

The attached application,

OR

United States Application Number or PCT International application number

15/876,225 Filed on 2018/1/22.

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

P20172929US00  
73168-US-PA

**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. Taiwan Semiconductor Manufacturing Co., Ltd.  
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,  
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

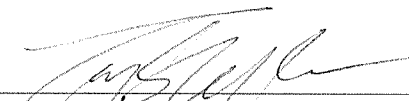
NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

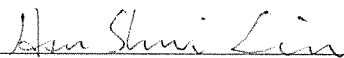
The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

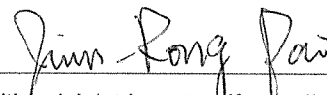
The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.


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**DECLARATION AND ASSIGNMENT  
FOR UTILITY OR DESIGN PATENT APPLICATION**

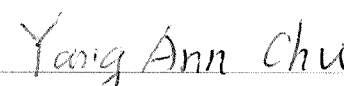
Signature:  Date: 2018/2/11  
Legal Name of Sole or First Inventor: Tsung-Sheng Kuo  
Residence: New Taipei City, Taiwan  
Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature:  Date: 2018. 2. 7  
Legal Name of Additional Joint Inventor, if any: Hsu-Shui Liu  
Residence: Taoyuan City, Taiwan  
Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature:  Date: 2018-2-7  
Legal Name of Additional Joint Inventor, if any: Jiun-Rong Pai  
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Signature:  Date: 2018 2. 7.  
Legal Name of Additional Joint Inventor, if any: Shou-Wen Kuo  
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Signature:  Date: 2018/2/17  
Legal Name of Additional Joint Inventor, if any: Wen-Chin Kan  
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Signature:  Date: 2018/2/5  
Legal Name of Additional Joint Inventor, if any: Yang-Ann Chu  
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